



# UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE  
United States Patent and Trademark Office  
Address: COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, Virginia 22313-1450  
www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/704,641	11/01/2000	Maximilian Albert Biberger	SSI-00700	4503
28960	7590	05/19/2004	EXAMINER	
HAVERSTOCK & OWENS LLP 162 NORTH WOLFE ROAD SUNNYVALE, CA 94086			KACKAR, RAM N	
			ART UNIT	PAPER NUMBER
			1763	

DATE MAILED: 05/19/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

## Office Action Summary

**Application No.**

09/704,641

**Applicant(s)**

BIBERGER ET AL.

**Examiner**

Ram N Kackar

**Art Unit**

1763

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

### Status

- 1) ☒ Responsive to communication(s) filed on 02 April 2004.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

### Disposition of Claims

- 4) ☒ Claim(s) 1-25, 29-31 and 33-38 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-25, 29-31 and 33-38 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

### Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some \* c) ☐ None of:
- 1) ☐ Certified copies of the priority documents have been received.
  - 2) ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  - 3) ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

### Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)  
Paper No(s)/Mail Date \_\_\_\_\_
- 4) ☐ Interview Summary (PTO-413)  
Paper No(s)/Mail Date \_\_\_\_\_
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: \_\_\_\_\_

## DETAILED ACTION

### *Claim Rejections - 35 USC § 103*

1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

2. Claims 1, 6-8, 15-17, 19- 20, 25, 29-31 and 33 are rejected under 35 U.S.C. 103(a) as being unpatentable over Edward Bok et al (Article Super critical Fluids for Single wafer Cleaning, Solid State Technology, June 1992) in view of Shigeru Ueno (JP 08206485).

Bok teaches a cluster tool configuration with a supercritical fluid cleaning module using carbon dioxide (Fig 4, 5 and Page 117 Col 3 and Page 120 lines 12-19), which is designed for high pressure (Page 118 Col 2), a transfer module with a robot coupled to it (Page 118 Col 3 last Para) and a non- supercritical module for etching (Page 119 Col 2 and Page 120 lines 12-19) and lower input valve for inlet and lateral valve for exit of fluid (Page 118 Col 3).

A non-supercritical module being attached to the transfer module is inherent in view of Bok teaching that chemical etching is usually followed by cleaning (Page 119 Col 2) and that the supercritical module would typically be used after HF (etching) process and would be ideally done in a cluster tool where substrate could be contaminant free between multiple process steps (Page 120 lines 12-19).

Bok however does not disclose a circulation line to circulate super critical fluid in the processing cavity.

Since circulation of supercritical fluid over work piece offers the advantages of continuous rinsing action on the substrate and reuse helps reduce cost and helps the environment, an alternative cleaning method has been proposed by several inventors.

Shigeru Ueno discloses recirculation passage (Abstract and Fig 1-7).

Therefore it would have been obvious to one of ordinary skill in the art at the time of invention to use a recirculation device for faster cleaning with advantage of cost and environmental friendliness.

3. Claims 2-5, 9-10 and 22-24 are rejected under 35 U.S.C. 103(a) as being unpatentable over Edward Bok et al (Article Super critical Fluids for Single wafer Cleaning, Solid State Technology, June 1992) in view of Shigeru Ueno (JP 08206485) as applied to claims 1, 6-8, 15-17, 19- 20, 25, 29-31 and 33 and further in view of Chen et al (US Patent 6110232).

Bok as modified by Shigeru Ueno teaches a cluster tool configuration with a supercritical fluid cleaning module using carbon dioxide (Fig 4, 5 and Page 117 Col 3 and Page 120 lines 12-19), which is designed for high pressure (Page 118 Col 2), a transfer module with a robot coupled to it (Page 118 Col 3 last Para) and a non- supercritical module for etching (Page 119 Col 2 and Page 120 lines 12-19) and lower input valve for inlet and lateral valve for exit of fluid (Page 118 Col 3).

Bok does not disclose the usual, necessary and obvious details of the transfer related apparatus for its cluster tool.

Art Unit: 1763

Chen et al disclose a multi chamber cluster tool and as part of that disclose a transfer module (Fig1-20) having an entrance (attached to load locks 12 and 14), a process module coupled to the transfer module (Fig3-32), a transfer mechanism coupled to the transfer module which is configured to move the work piece between the entrance, and any other processing module coupled to it (Fig 3-28), means for injecting inert gas like nitrogen to allow the pressure in the transfer chamber to be slightly positive (Col 2 line 22-25), two hand off stations (Fig 3-14 and 12) adapted in two load locks at the entrance of the transfer module, non supercritical module to be a semiconductor module of the type of an etch, PVD or CVD (Col 1 line 14-21), the transfer mechanism to be a central robot (Fig 3-28) adapted in a circular configuration, the robot arm to comprise an extendable arm and an end effector (Fig 3-28) and the transfer module to be vacuum capable (Fig 1-20).

Therefore it would have been obvious to one having ordinary skill in the art at the time invention was made to integrate to Bok's cluster tool the transfer module and accessories in order to make Bok's cluster tool realize the advantage of supercritical processing step with other processing on a wafer without taking the wafer out of clean environment between steps and to have higher throughput.

4        Claims 11-12 are rejected under 35 U.S.C. 103(a) as being unpatentable over Edward Bok et al (Article Super critical Fluids for Single wafer Cleaning, Solid State Technology, June 1992) in view of Shigeru Ueno (JP 08206485) as applied to claims 1, 6-8, 15-17, 19- 20, 25, 29-31 and 33 and further in view of White et al (US Patent 6235634).

Art Unit: 1763

Bok discloses a robot as transfer mechanism but does not disclose the transfer mechanism to comprise a track configuration. White et al disclose a robot on a track configuration (Fig 2 and Col 6 lines 30-59).

As track configuration allows for unrestricted placement of processing modules along the track, it would have been obvious to one having ordinary skill in the art at the time invention was made to have a track configured robot of White as a transfer mechanism for Bok.

5      Claims 13-14, 18 and 21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Edward Bok et al (Article Super critical Fluids for Single wafer Cleaning, Solid State Technology, June 1992) in view of Shigeru Ueno (JP 08206485) as applied to claims 1, 6-8, 15-17, 19- 20, 25, 29-31 and 33 and further in view of Adachi et al (US Patent 6077321).

Bok teaches a cluster tool configuration with a supercritical fluid cleaning module using carbon dioxide (Fig 4, 5 and Page 117 Col 3 and Page 120 lines 12-19), which is designed for high pressure (Page 118 Col 2), a transfer module with a robot coupled to it (Page 118 Col 3 last Para) and a non- supercritical module for etching (Page 119 Col 2 and Page 120 lines 12-19), lower input valve for inlet and lateral valve for exit of fluid (Page 118 Col 3) and sealing means (Fig 4-a).

Bok does not disclose a robot with extendable dual arm and end effector and an antechamber coupled to a transfer module and a supercritical processing module.

Adachi et al discloses a cluster tool with extendable arm and dual arm with dual end effectors (Fig 1) designed for substrate processing with cleaning and drying and disclose a small volume antechamber (buffer chamber) between transfer module and a cleaning /drying chamber in order to isolate the environment of film forming module from cleaning /drying module (Fig

Art Unit: 1763

1). Adachi et al go a great length in explaining how the use of antechamber allows atmospheres to be controlled in each module to maintain environments for optimum processing (Col 5 -11).

With this teaching on hand, it would have been obvious to one having ordinary skill in the art to have an antechamber like that of Adachi et al to install in front of supercritical module of Bok so as to provide isolation between high pressure module of supercritical processing and low pressure transfer module or any other module configured for a different processing, attached to it.

6 Claims 34- 38 are rejected under 35 U.S.C. 103(a) as being unpatentable over Edward Bok et al (Article Super critical Fluids for Single wafer Cleaning, Solid State Technology, June 1992) in view of Shigeru Ueno (JP 08206485) as applied to claims 1, 6-8, 15-17, 19- 20, 25, 29- 31 and 33 and further in view of Racette et al (US Patent 6355072).

Bok as modified by Shigeru Ueno teaches a cluster tool configuration with a supercritical fluid cleaning module using carbon dioxide (Fig 4, 5 and Page 117 Col 3 and Page 120 lines 12-19), which is designed for high pressure (Page 118 Col 2), a transfer module with a robot coupled to it (Page 118 Col 3 last Para) and a non- supercritical module for etching (Page 119 Col 2 and Page 120 lines 12-19) and lower input valve for inlet and lateral valve for exit of fluid (Page 118 Col 3).

Shigeru Ueno does not disclose additional solvent line connected to the workpiece cavity through connection to circulating line.

Racette et al disclose a vessel for supercritical processing (Col 4 lines 19-34) where the supercritical fluid undergoes cycling in addition to solvent (Fig 2 and Col 13 lines 3-18) connected through pumps (240, 242).

Art Unit: 1763

Therefore it would have been obvious for one of ordinary skill in the art at the time of invention to have additional lines for solvent to enable faster cleaning using solvents in addition to supercritical fluid.

### ***Response to Amendment***

Applicant's arguments filed 4/2/2004 have been fully considered but they are not persuasive.

Applicant adds a limitation that the circulation line is configured to circulate fluid in supercritical state along the circulation line and states that Shigeru Ueno does not disclose this since the abstract does not specifically say that the fluid flow is supercritical along the circulation line. This argument is not persuasive since the circulation line just like the specification discloses only a circulation pump.

### ***Conclusion***

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ram N Kackar whose telephone number is 571 272 1436. The examiner can normally be reached on M-F 8:00 A.M to 5:P.M.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Gregory Mills can be reached on 571 272 1439. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.




Application/Control Number: 09/704,641

Page 8

Art Unit: 1763

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

RK

  
GREGORY MILLS  
SUPERVISORY PATENT EXAMINER  
TECHNOLOGY CENTER 1700